

TGn Sync, WWiSE and Mitmot closing report

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Submission

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Abstract

- ➔ This document provides an update on the joint proposal effort this week among TGn Sync, WWiSE, and Mitmot

Procedural Updates

- ➔ Adopted a process for creating the joint proposal
 - Adopted a decision making procedure
 - Agreed on web tools to help facilitate document sharing and conference calls
- ➔ Established a firm and aggressive schedule for F2F and conference calls

PHY/MAC Teams Update

- ➔ Created a sequence of discussion points
- ➔ Discussed motions for adding draft text to the joint proposal
- ➔ Fielded detailed technical presentations on topics of mutual interest
- ➔ Created tiger teams to accelerate technical progress

Next Steps

- ➔ Weekly conference calls, starting next week
 - One for the MAC, one for the PHY
- ➔ F2F meeting in Japan in August
- ➔ Will upload one week prior to IEEE in Anaheim either a draft joint proposal or a progress report

Joint Proposal Timeline



